

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

Claims 1-25 (canceled)

26. (currently amended) A method for checking an electronic component package, comprising:

~~a semiconductor chip having a first surface and a second surface, said first surface comprising multiple pads; and~~

~~an encapsulating structure comprising a non-black material and over said second surface.~~

providing said electronic package with a mark; and

reading said mark using a laser code reader.

27. (currently amended) The electronic component method of claim 26, ~~comprising multiple bumps connected to multiple pads, wherein said mark comprises a bar code.~~

28. (currently amended) The ~~electronic component~~ method of claim 26, ~~further comprising a substrate, wherein said semiconductor chip is connected to said substrate in a flip-chip fashion, wherein said mark comprises an identity for a product.~~

29. (currently amended) The ~~electronic component~~ method of claim 26, wherein said ~~second surface comprises a mark under said encapsulating structure~~ mark comprises an identity for a manufacturer.

30. (currently amended) The ~~electronic component~~ method of claim ~~29~~ 26, wherein said ~~mark comprises a number, wherein said electronic package comprises a semiconductor chip and a protecting structure, said semiconductor chip having a surface with said mark, said protecting structure being over said mark, wherein said mark is visible through said protecting structure.~~

31. (currently amended) The ~~electronic component~~ method of claim ~~29~~ 30, wherein said ~~mark comprises a bar code, surface further comprises multiple pads.~~

32. (currently amended) The ~~electronic component~~ method of claim ~~29~~ 30, wherein said ~~mark comprises an identity for a product, semiconductor chip has another surface with multiple pads.~~

33. (currently amended) The ~~An electronic component of claim 29, wherein said package comprising a mark comprises an identity for a manufacturer, read by a laser code reader.~~

34. (currently amended) The electronic ~~component~~ package of claim ~~29~~33, wherein said mark is ~~visible through said encapsulating structure~~. comprises a bar code.

35. (currently amended) The electronic package of claim 33, wherein said ~~laser-readable~~ mark comprises an identity for a product.

36. (currently amended) The electronic package of claim 33, wherein said ~~laser-readable~~ mark comprises an identity for a manufacturer.

37. (currently amended) The electronic package of claim 33 comprising a semiconductor chip and a protecting structure, said semiconductor chip having a surface with said ~~laser-readable~~ ~~readable~~ mark, said protecting structure being over said ~~laser-readable~~ mark, wherein said mark is visible through said protecting structure.

38. (currently amended) A semiconductor chip having a surface with a ~~laser-readable~~ mark read by a laser code reader.

39. (currently amended) The semiconductor chip of claim 38, wherein said ~~laser-readable~~ mark comprises a bar code.

40. (currently amended) The semiconductor chip of claim 38, wherein said ~~laser-readable~~ mark comprises an identity for a product.

41. (currently amended) The semiconductor chip of claim 38, wherein said ~~laser-readable~~ mark comprises an identity for a manufacturer.

42. (previously presented) The semiconductor chip of claim 38, wherein said surface further comprises multiple pads.

43. (previously presented) The semiconductor chip of claim 38, wherein said semiconductor chip has another surface with multiple pads.

44. (previously presented) An electronic package comprising:

a semiconductor chip having a first surface with multiple pads and a second surface with a mark; and

a protecting structure over said mark, wherein said mark is visible through said protecting structure.

45. (currently amended) The electronic package of claim 44, wherein said mark comprises a bar code.

46. (previously presented) The electronic package of claim 44, wherein said mark comprises a number.

47. (previously presented) The electronic package of claim 44, wherein said mark comprises an identity for a product.

48. (previously presented) The electronic package of claim 44, wherein said mark comprises an identity for a manufacturer.

49. (previously presented) The electronic package of claim 44, wherein said mark is colored.

50. (previously presented) An electronic package comprising:

a semiconductor chip having a surface with a mark comprising a number, a bar code, or an identity for a product or a manufacturer; and

a protecting structure over said mark, wherein said mark is visible through said protecting structure.

51. (previously presented) The semiconductor chip of claim 50, wherein said surface further comprises multiple pads.

52. (previously presented) The semiconductor chip of claim 50, wherein said semiconductor chip has another surface with multiple pads.